









# PRODUCT DATASHEET



- ► SuperFlux (Piranha)
- ► 5mm Round 5.05t
- ► True Green (525nm)

N0G18P71S



# SuperFlux 5mm





SuperFlux 5 mm

#### **APPLICATIONS:**

- Indicator
- Signal Light

**FEATURES:** 

- Package: PTH Through Hole 4-Pins Package
- Forward Current: 20mA Forward Voltage (typ.): 3.5V
- Luminous Intensity (typ.): 4000mcd@20mA
- Colour: True Green Wavelength: 525nm Viewing angle: 70°
- **Materials:** 
  - Die: InGaN/GaN
  - Resin: Epoxy (Water Clear)
  - L/T Finish: Ag plated
- Operating Temperature: -20~+80°C Storage Temperature: -30~+100°C
- **ESD (HBM):** 150V
- **Grouping parameters:** 
  - Forward voltage
  - Luminous intensity
  - **Dominant Wavelength**
- Soldering methods: Wave Soldering
- MSL: acc. to JEDEC Level 3
- Packing: 60pcs/tube; 6300pcs/carton



### **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I <sub>F</sub>	30	mA
Pulse Forward Current Duty 1/10 at 10KHz	IPF	100	mA
Power Dissipation	PD	120	mW
Reverse Current @5V	I <sub>R</sub>	50	μА
Electrostatics Discharge (HBM)	ESD	150	V
Operating Temperature	T <sub>OPR</sub>	-20~+80	°C
Storage Temperature	T <sub>STG</sub>	-30~+100	°C

# Electrical & Optical Characteristics (Ta=25°C)

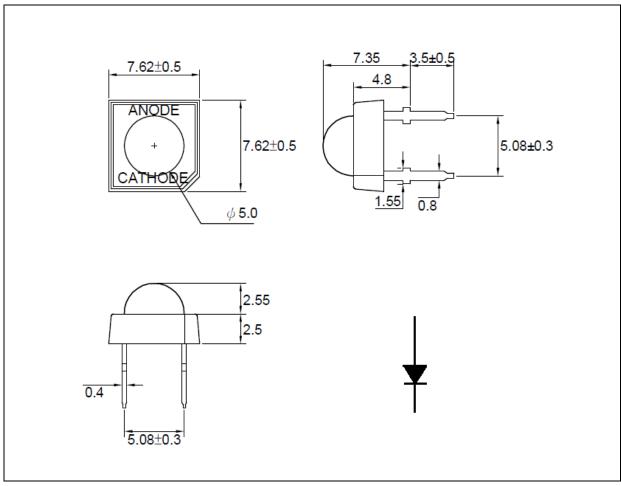
Parameter	Symbol	Values			Unit	Test
Parameter		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V <sub>F</sub>		3.5	4.0	V	I <sub>F</sub> =20mA
Luminous Intensity	I <sub>V</sub>	2700	4000		mcd	I <sub>F</sub> =20mA
Dominant Wavelength	$\lambda_{D}$		525		nm	I <sub>F</sub> =20mA
Peak Wavelength	$\lambda_{ extsf{P}}$		518		nm	I <sub>F</sub> =20mA
Spectral Half Width	Δλ		36		nm	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>		70		deg	I <sub>F</sub> =20mA

<sup>1.</sup> Luminous intensity (I<sub>V</sub>) ±15%, Forward Voltage (V<sub>F</sub>) ±0.1V, Viewing angle(2 $\theta_{1/2}$ ) ±5%



# **OUTLINE DIMENSION:**

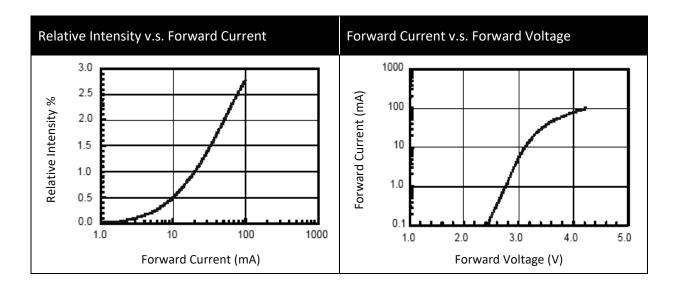
## Package Dimension:

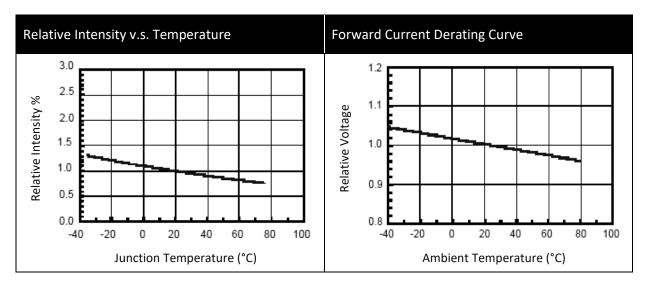


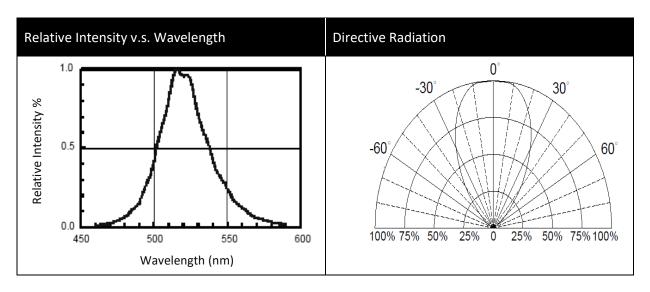
- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



#### **ELECTRO-OPTICAL CHARACTERISTICS:**







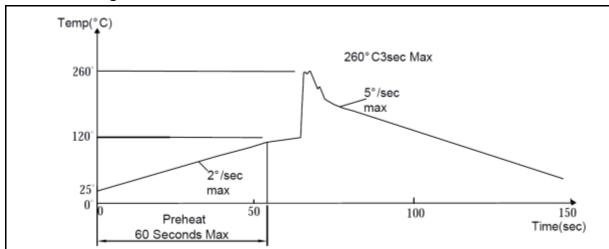


#### **RECOMMENDED SOLDERING PROFILE:**

#### **DIP Iron:**

- Soldering Iron 30W Max.
- Temperature 350°C Max.
- Soldering Time 3 seconds Max. One time only.
- Distance 2mm Min. (from solder joint to body).

#### **Wave Soldering Profile:**



• Dip Soldering

Preheat: 120°C Max

Preheat time: 60seconds Max

• Ramp-up

2°C/sec(max)

Ramp-Down: -5°C/sec(max)

Solder Bath: 260°C Max

Dipping Time: 3 seconds Max

• Distance: 2mm Min (From solder joint to body)

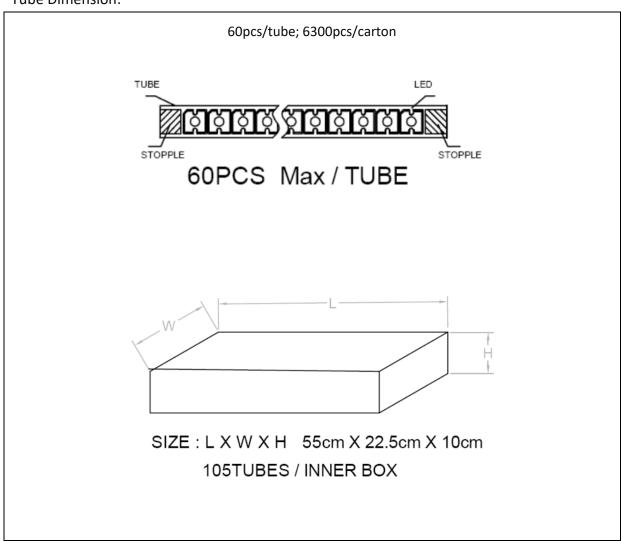
#### Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.
- 3. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.



## **PACKING SPECIFICATION:**

#### **Tube Dimension:**





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

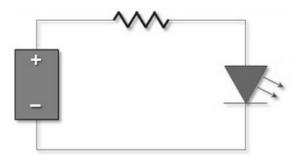
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 6hrs and <5%RH, for reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	07/07/2015	Datasheet set-up.
A1.1	26/06/2022	Add -S ending.